

SPECIFICATION

(产品规格书)

CUSTOMER : _____
(客户)

(产品型号)

(规格书编号)

DESCRIPTION : _____
(产品描述)

DATE : 21/10/2008
(日期)

R&D DEPARTMENT (技术部)		
APPROVED (核准)	CHECKED (审核)	PREPARED (制定)
		谷明江

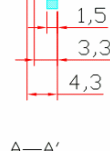
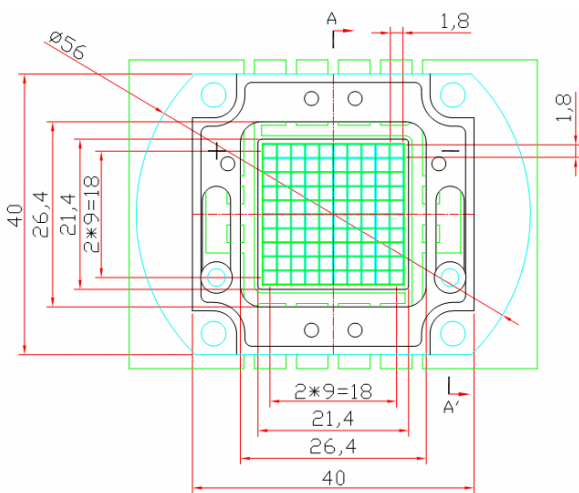
深圳市立洋光电有限公司

Feature

(特性)

- ◆ 100W High Power LED
(100W 大功率 LED)
- ◆ Package : SMT Package
(贴片式外形)
- ◆ Half Angle ($2\Theta_{1/2}$):120°
(视角: 120°)
- ◆ Lens Color : Water Clear
(透镜颜色: 无色透明)

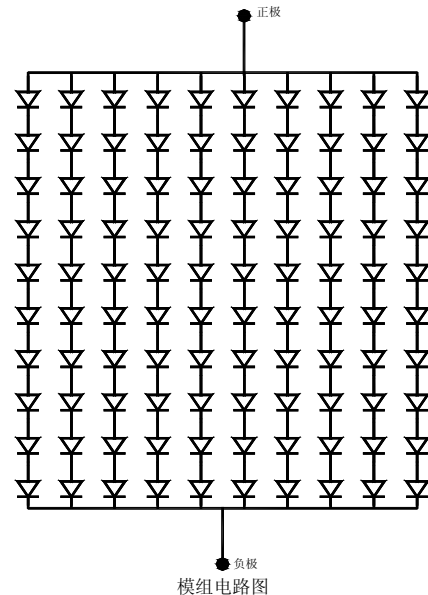
Package Dimensions (外观尺寸)



Applications

(应用)

- ◆ General Lighting
(普通照明)
- ◆ Advertisement
(广告灯)
- ◆ Architectural Lighting
(建筑照明)
- ◆ Street Lamps
(路灯)



Notes:

1. All dimensions are in millimeters.
(所有尺寸以毫米为单位)
2. Tolerance is ± 0.25 unless otherwise noted
(未标注公差为: ± 0.25)

Part NO. (产品型号)	LED Chip		LED Emitted Color (LED 发光颜色)	Lens Color (透镜颜色)	Description (描述)
	Material (材质)	Emitted Color (发光颜色)			
	InGaN /GaN	Blue(蓝色)	White(白色)	Clear(透明)	Water Clear (无色透明)

Part NO.:

■ Electrical/Optical Characteristics (At T_A=25°C)

(光电参数)

Parameter (参数)	Symbol (符号)	Conditions (测试条件)	Min. (最小值)	Avg. (平均值)	Max. (最大值)	Units (单位)
Luminous Flux (发光强度)	Φ	I _F =3.5A	6000	--	7000	lm
Color Temperature (色温)	CCT	I _F =3.5A	6000	6500	7000	K
Forward Voltage (正向压降)	V _F	I _F =3.5A	30	--	35	V
Thermal Resistance Junction To Board (热阻)	RΘ _{J-B}	I _F =3.5A	--	10	--	°C/W
Reverse Current (反向漏电流)	I _R	V _R =5V	--	--	1	μA
Viewing Angle ^[1] (发光角度)	2Θ _{1/2}	I _F =3.5A	--	140	--	Deg

■ Absolute Maximum Rating(At T_A=25°C)

(极限参数)

Parameter (参数)	Symbol (符号)	Ratings (数值)	Units (单位)
Power Dissipation (功率)	P _D	100	W
Continuous Forward Current (正向输入电流)	I _F	3.5	A
LED Junction Temperature (结点温度)	T _J	120	°C
Reverse Voltage (反向电压)	V _R	5	V
Operating Temperature Range (工作温度)	T _{OPR}	-30°C To +60°C	
Storage Temperature Range (储存温度)	T _{STG}	-40°C To +100°C	
Manual Soldering Temperature (手工焊接温度)	T _{SOL}	350°C± 20°C For 3~5 Seconds	
ESD Sensitivity (抗静电能力)	ESD	20000V HBM	

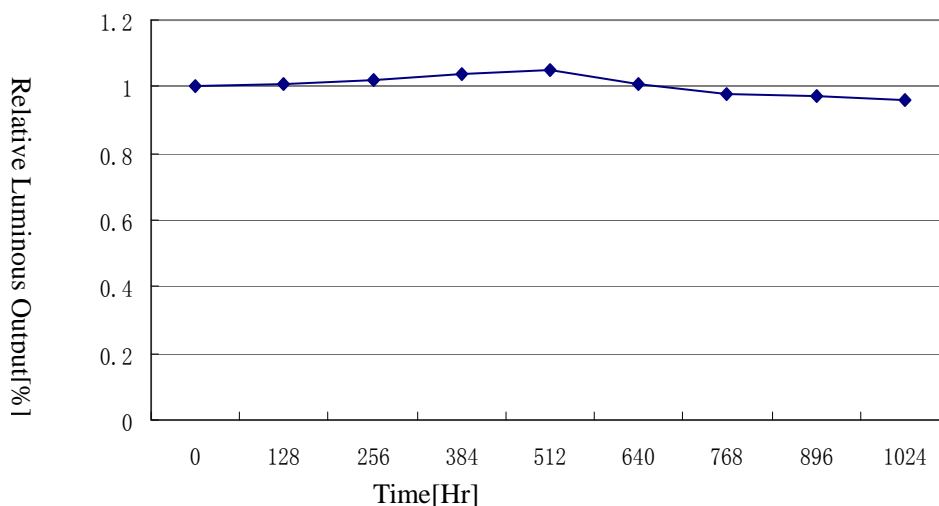
Part NO.:

Room Temperature Operating Life Reliability Test Result

常温点亮信耐性结果

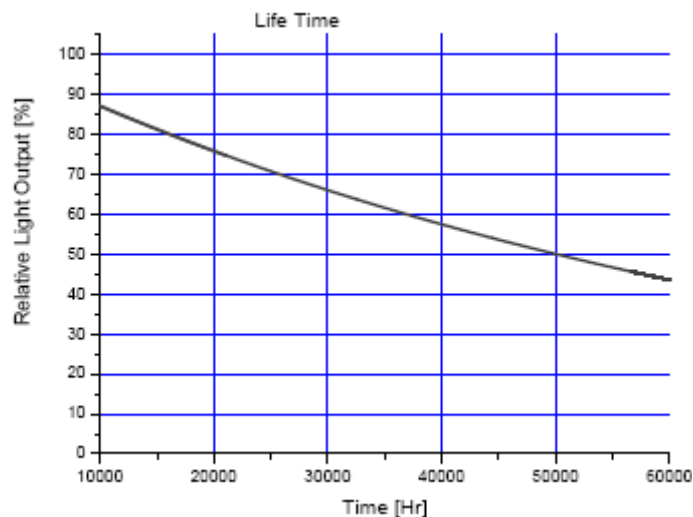
($T_a=25^{\circ}\text{C}$, $I_f=2.1\text{A}$) Use SSC circuit board & heat sink ($T_j=50^{\circ}\text{C}$)

使用 SSC 带热沉电路板 ($T_j=50^{\circ}\text{C}$)



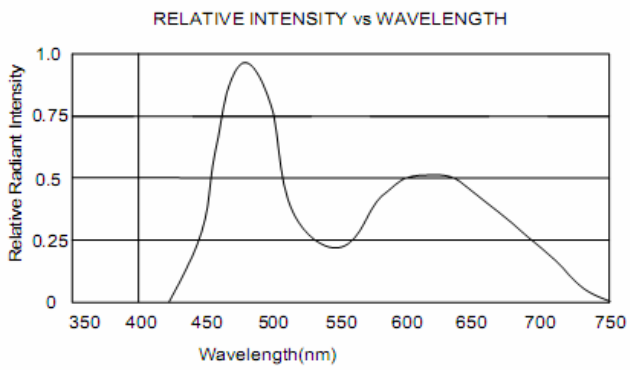
1000HR 3.5% degradation (1000 小时衰减 3.5%)

Life Time graph (使用寿命)

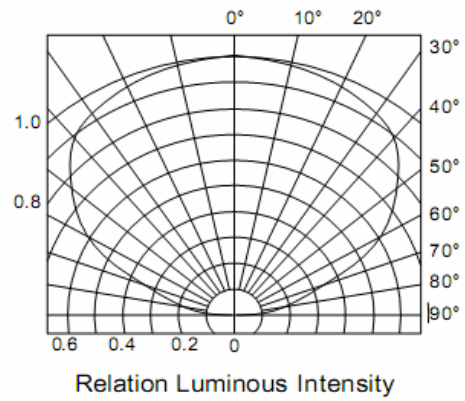


50000HR 50% degradation (50000 小时衰减 50%)

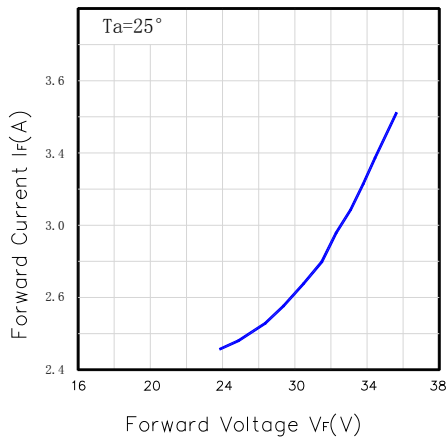
Spectrum Distribution(光谱分布图)



Radiation Diagram(角度图)



V_F - I_F Characteristics(V_F - I_F 曲线)



Precautions For use

(1) Storage

In order to avoid absorption of moisture it is recommended that the products are stored in the dry box (or dessicator) with a dessicant. Alternatively the following environment is recommended:

Storage temperature :5°C~30°C Humidity:60% HR max.

- (2) Any mechanical force or any excess vibration should be avoided during the cooling process after soldering.
- (3) Components should not be mounted on distorted Printed Circuit Boards.
- (4) Devices should not be used in any type of fluid such as water,oil,organic solvents etc. When cleaning is required,IPA should be used.
- (5) Devices should be soldered within 7 days after opening the moisture-proof packing.
- (6) ESD Precautions.Static Electricity and surge damages LEDs.
It is recommended that wrist bands or anti-electrostatic gloves be used when handling the LEDs.All devices,equipment and machinery should be properly grounded.
- (7) It is recommended to use individual resistors when LEDs are used in parallel circuits in order to improve performance.

使用说明

一、贮存:

为避免吸潮建议将产品贮存在放有干燥剂的干燥柜中，贮存温度为：5°C~30°C，湿度： $\leq 60\%HR$ 。

二、产品在焊锡后冷却过程中避免机械压力和过大震动。

三、禁止焊接在变形PCB板上。

四、产品不得接触水、油、有机溶液。

五、打开防潮包装后7天内产品使用完毕。

六、防静电要求:

使用产品时，必须戴防静电环或防静电手套，所有设备、装置、机台必须有效接地。

七、将产品与电阻配合使用效果更佳